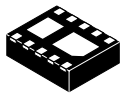


# MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

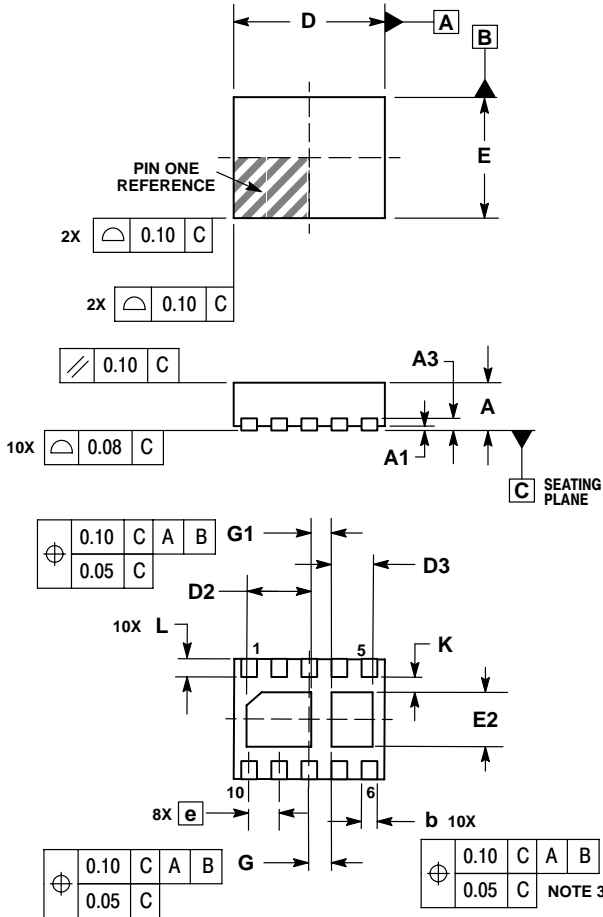
ON Semiconductor®



**WDFN10 2.5x2, 0.5P**  
CASE 516AA-01  
ISSUE C

DATE 06 FEB 2007

SCALE 4:1

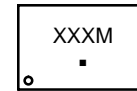


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS			
DIM	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	---	0.05
A3	0.20 REF		
b	0.20	0.25	0.30
D	2.50 BSC		
D2	0.97	1.08	1.18
D3	0.57	0.68	0.78
e	0.50 BSC		
E	2.00 BSC		
E2	0.80	0.90	1.00
G	0.375 BSC		
G1	0.35 BSC		
K	0.20	---	---
L	0.20	0.30	0.40

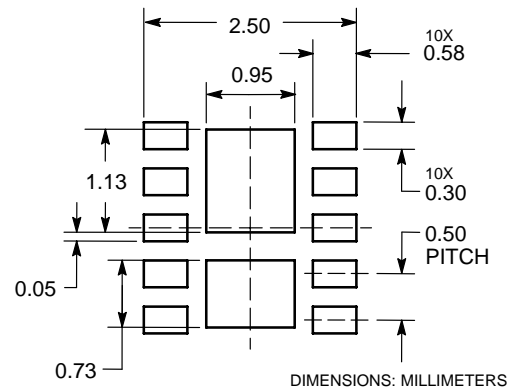
**GENERIC MARKING DIAGRAM\***



- XXX = Specific Device Code
- M = Date Code
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

**SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>WDFN10 2.5X2, 0.5P</b>	<b>PAGE 1 OF 2</b>



ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION. REQ. BY C. GIOIA.	19 JAN 2006
A	ADDED NOMINAL VALUES AND MODIFIED DIMENSIONS. MODIFIED SOLDERING FOOTPRINT VALUES. ADDED MARKING DIAGRAM. REQ. BY W. CLEMENS.	27 NOV 2006
B	MODIFIED SOLDERING FOOTPRINT VALUES. REQ. BY W. CLEMENS.	23 JAN 2007
C	CORRECTED G AND G1 VALUES TO 0.375 & 0.35 RESPECTIVELY. REQ. BY W. CLEMENS.	06 FEB 2007

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